ABSTRACT

The surface of a material for an electronic device is flattened by irradiating the surface of the material with at least part of plasma components, while supplying a liquid to the surface of the material for an electronic device. There are provided a method of treating the surfaces for favorably flattening the surface of the material for an electronic device or of the substrate for an electronic device, while suppressing damage to the material or to the substrate, and an apparatus for treating the surfaces.

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